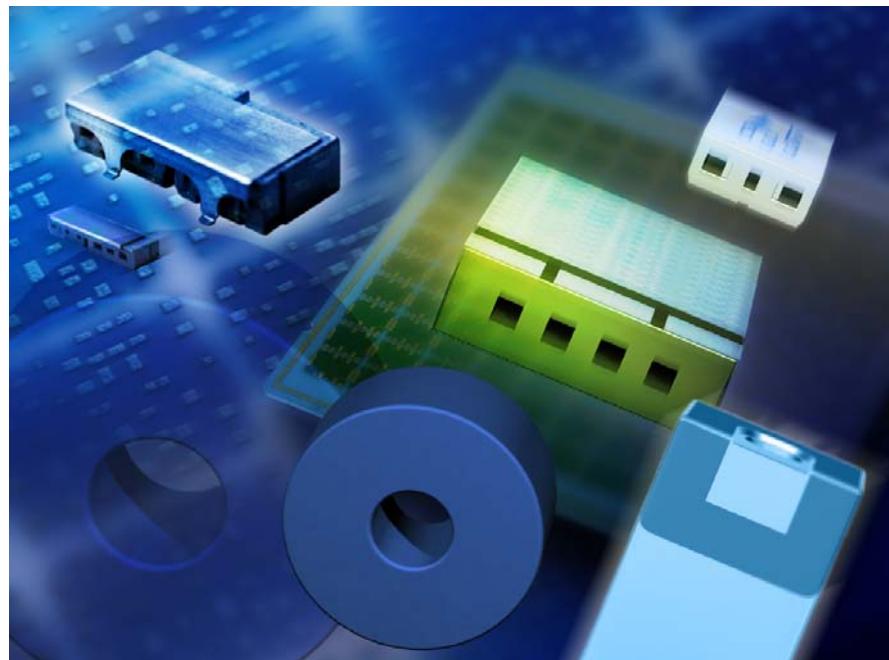


Preliminary Datasheet



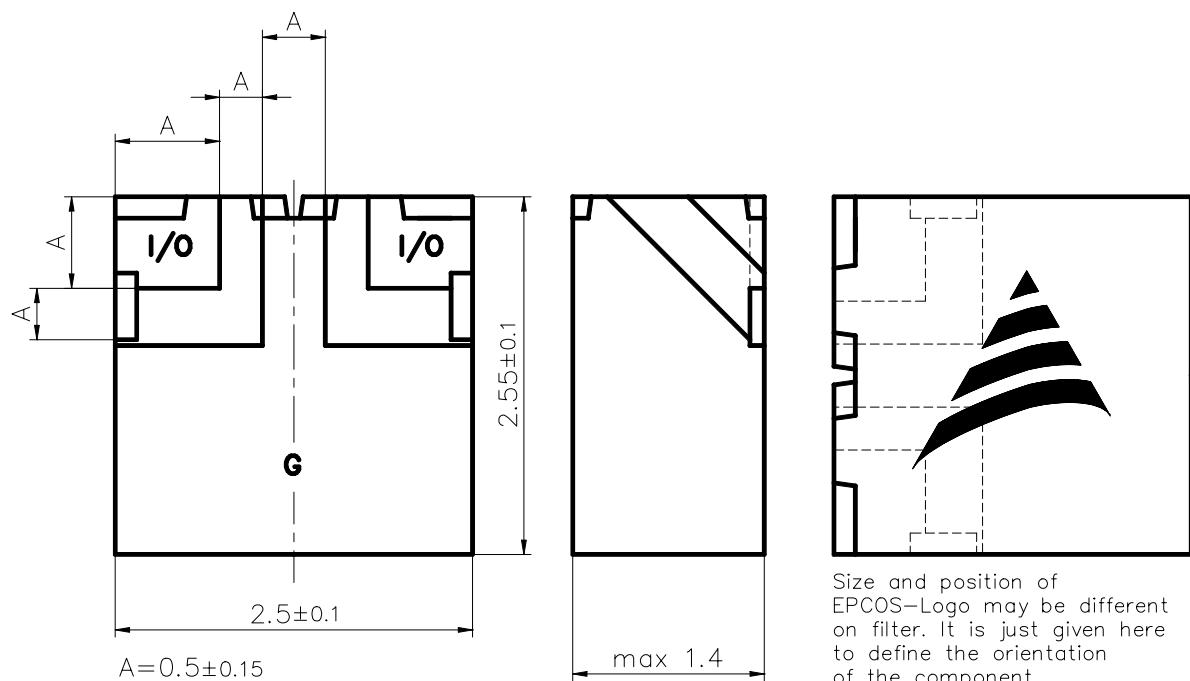
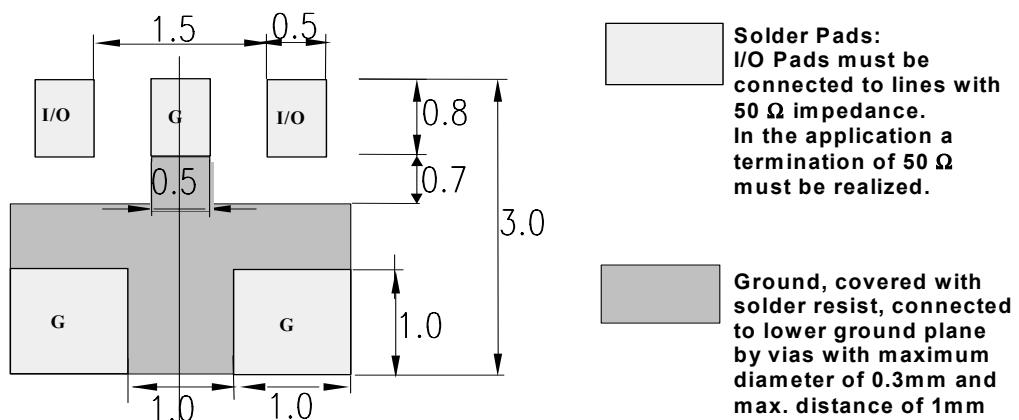
Features

- Low Profile (maximum height 1.4 mm)
- SMD filter consisting of coupled resonators with stepped impedances
- Low losses
- High attenuations at GSM (900, 1800) and UMTS bands
- High attenuation at 2 times center frequency
- (NdBa)TiO₃ ($\epsilon_r = 88$ / $TC_f = 0 \pm 10$ ppm/K) with a coating of copper (10 μ m) and tin (>5 μ m)
- Excellent reflow solderability, no migration effect due to copper/tin metallization

Index

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Page 4	<ul style="list-style-type: none">• Processing information• Soldering requirements• Delivery mode

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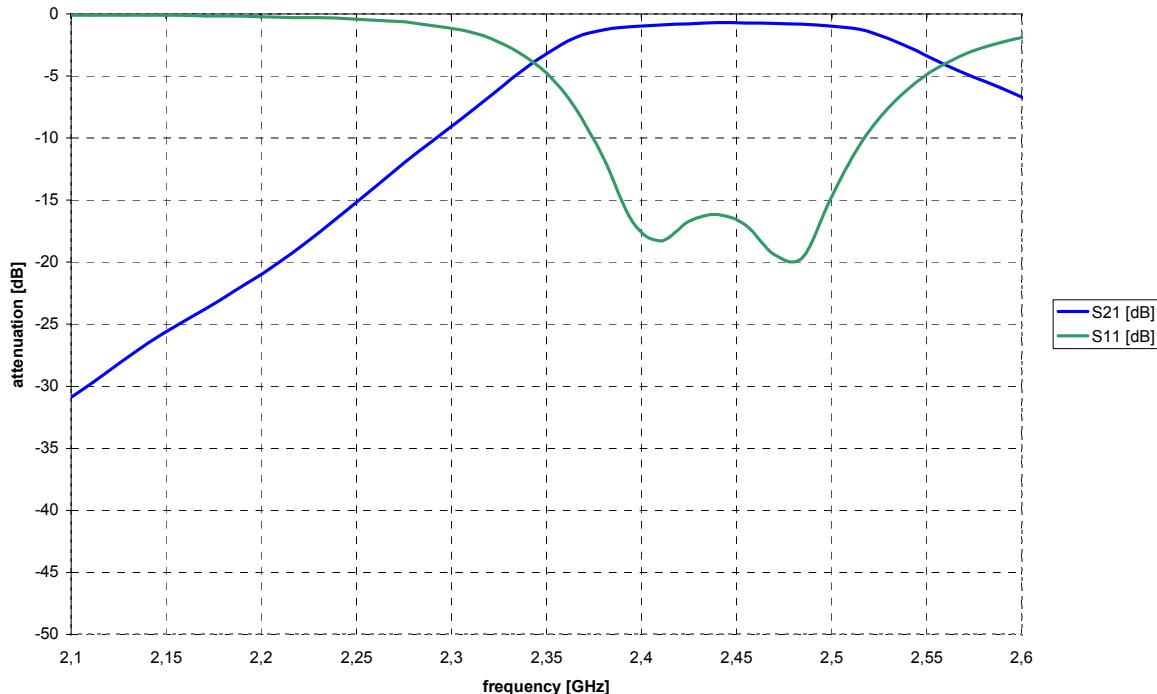
Preliminary Datasheet
Dimension Limits , Marking

Recommended footprint


Preliminary Datasheet
Characteristics

		min.	typ.	max.	
Center frequency	f_c	-	2.450	-	GHz
Insertion loss	α_{IL}		1.4	1.8	dB
Passband (2400- 2500)	B	100			MHz
Amplitude ripple (peak - peak)	$\Delta\alpha$		0.4	0.8	dB
Standing wave ratio	SWR		1.5	2.0	
Impedance	Z		50		Ω
Attenuation	α				
at DC to 880 MHz		50	55		dB
at 880 to 960 MHz		45	50		dB
at 960 to 1990 MHz		40	45		dB
at 1990 to 2100 MHz		25	30		dB
at 2100 to 2170 MHz		20	25		dB
at 3000 to 3200 MHz		15	20		dB
at 3200 to 3500 MHz		20	25		dB
at 3500 to 4600 MHz		27	30		dB
at 4800 to 5000 MHz		25	30		dB

Maximum ratings

IEC climatic category (IEC 68-1)	- 40 / + 90/56	
Operating temperature	T_{op} - 40 / + 85	°C

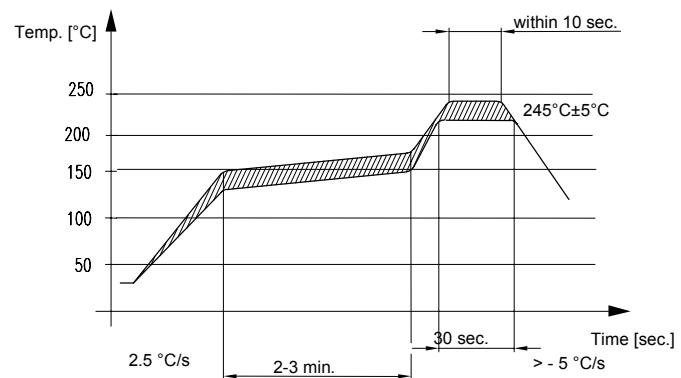
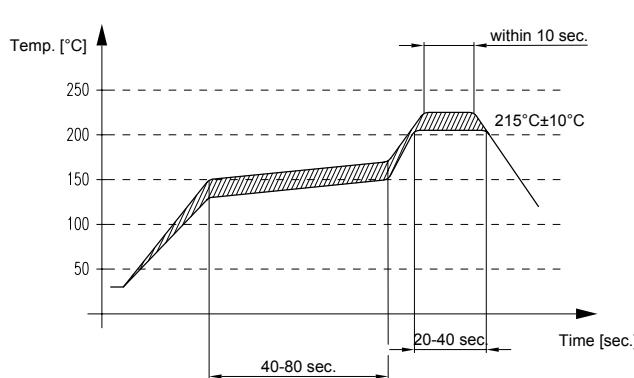
Typical passband characteristics


Preliminary Datasheet
Processing information

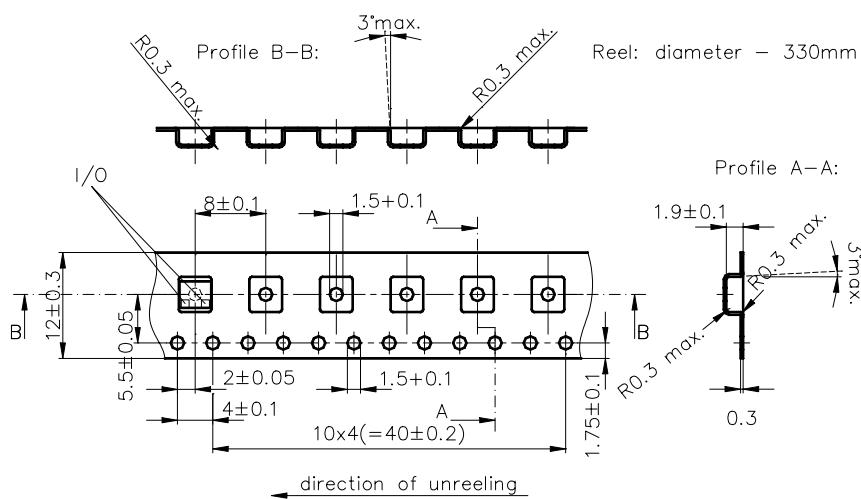
- Wettability to IEC 68-2-58: $\geq 75\%$ (after aging)

Soldering Requirements

	Profile for eutectic SnPb solder paste	Profile for leadfree solder paste	
Soldering type	reflow	reflow	
Maximum soldering temperature (measuring point on top surface of the component)	235 (max. 2 sec.) 225 (max. 10 sec.)	260 (max. 2 sec.) 250 (max. 10 sec.)	°C °C

Recommended soldering conditions (infrared):

Delivery mode

- Blister tape acc. to IEC 286-3, grey
- Pieces/tape: 4000



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